

L Number	Hits	Search Text	DB	Time stamp
1	374938	(test wiring circuit) adj2 (board substrate)	USPAT;	2003/04/15 15:43
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
8	257738	spring coil) near6 (ball bump lead contact)	IBM_TDB   USPAT;	2003/04/15 15:45
	201100	(spring con) heard (ball burns read contact)	US-PGPUB;	2000/04/10 10.40
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
15	22662	((test wiring circuit) adj2 (board substrate)) and ((spring coil)	USPAT;	2003/04/15 15:46
		near6 (ball bump lead contact))	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM_TDB	
22	3450	(((test wiring circuit) adj2 (board substrate)) and ((spring coil)	USPAT;	2003/04/15 15:56
		near6 (ball bump lead contact))) and (324/\$.ccls. 361/\$.ccls.)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
29	6240	324/754,765.ccls.	IBM_TDB USPAT;	2003/04/15 15:47
23	0240	024/104,100.0013.	US-PGPUB:	2000/04/10 10.4/
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
36	494	(((test wiring circuit) adj2 (board substrate)) and ((spring coil)	USPAT;	2003/04/15 15:53
		near6 (ball bump lead contact))) and 324/754,765.ccls.	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM_TDB	
43	420130	(ball bump lead contact) near12 (opening aperture aperature	USPAT;	2003/04/15 15:56
		via hole)	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM_TDB	
50	29251	((spring coil) near6 (ball bump lead contact)) near12 (opening	USPAT;	2003/04/15 15:56
		aperture aperature via hole)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
57	2990	((test wiring circuit) adj2 (board substrate)) and ((ball bump	IBM_TDB USPAT;	2003/04/15 15:56
"	2000	lead contact) near12 (opening aperture aperature via hole))	US-PGPUB;	2300/04/10 10:00
		and (((spring coil) near6 (ball bump lead contact)) near12	EPO; JPO;	
		(opening aperture aperature via hole))	DERWENT;	
64	440	((/heat wising circuit) adio /heard cubatanta \ 4 (/heat	IBM_TDB	2002/04/45 40:42
64	442	(((test wiring circuit) adj2 (board substrate)) and ((ball bump lead contact) near12 (opening aperture aperature via hole))	USPAT; US-PGPUB;	2003/04/15 16:16
		and (((spring coil) near6 (ball bump lead contact)) near12	EPO; JPO;	
		(opening aperture aperature via hole))) and (324/\$.ccls.	DERWENT;	
		361/\$.ccls.)	IBM_TDB	
71	4376	324/765-769.ccls.	USPAT;	2003/04/15 16:17
			US-PGPUB; EPO; JPO;	
			DERWENT:	
			IBM TDB	
78	11	(((test wiring circuit) adj2 (board substrate)) and ((ball bump	USPAT;	2003/04/15 16:18
		lead contact) near12 (opening aperture aperature via hole))	US-PGPUB;	
		and (((spring coil) near6 (ball bump lead contact)) near12	EPO; JPO;	
		(opening aperture aperature via hole))) and 324/765-769.ccls.	DERWENT; IBM TDB	
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